

# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
<b>CONVEYING PARTY DATA</b>													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Alex HSU</td> <td>03/19/2009</td> </tr> <tr> <td>Shih-Chi FU</td> <td>03/19/2009</td> </tr> <tr> <td>Feng-Jia SHIU</td> <td>03/19/2009</td> </tr> <tr> <td>Chia-Shiung TSAI</td> <td>03/19/2009</td> </tr> </tbody> </table>		Name	Execution Date	Alex HSU	03/19/2009	Shih-Chi FU	03/19/2009	Feng-Jia SHIU	03/19/2009	Chia-Shiung TSAI	03/19/2009		
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<b>PROPERTY NUMBERS Total: 1</b>													
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<b>CORRESPONDENCE DATA</b>													
<p>Fax Number: (214)200-0853  <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 9727398635</p> <p>Email: lydia.eppshilliard@haynesboone.com</p> <p>Correspondent Name: David M. O'Dell</p> <p>Address Line 1: HAYNES AND BOONE, LLP - IP Section</p> <p>Address Line 2: 2323 Victory Avenue, Suite 700</p> <p>Address Line 4: Dallas, TEXAS 75219</p>													
ATTORNEY DOCKET NUMBER:	24061.1219												
NAME OF SUBMITTER:	David M. O'Dell												

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**PATENT**  
**REEL: 022614 FRAME: 0972**

Total Attachments: 3

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**ASSIGNMENT**

WHEREAS, we,

- |     |                  |    |                                                                                                   |
|-----|------------------|----|---------------------------------------------------------------------------------------------------|
| (1) | Alex Hsu         | of | 3F, No. 42, Yuanhou Street<br>Hsinchu City 300, Taiwan, R.O.C.                                    |
| (2) | Shih-Chi Fu      | of | 4F, No. 41, Lane 87, Fuyang Street, Sinyi District<br>Taipei City 110, Taiwan, R.O.C.             |
| (3) | Feng-Jia Shiu    | of | No. 3, Alley 22, Lane 289, Syuefu E. Road<br>Jhudong Township, Hsinchu County 310, Taiwan, R.O.C. |
| (4) | Chia-Shiung Tsai | of | No. 5, 50 Alley, 62 Lane, Gua-Tsuey Road<br>Hsin-Chu, Taiwan, R.O.C.                              |

have invented certain improvements in

**METHOD OF MEASUREMENT IN SEMICONDUCTOR FABRICATION**

for which we have executed an application for Letters Patent of the United States of America,

\_\_\_\_\_ of even date filed herewith; and  
  x   filed on March 31, 2009 and assigned application no. 12/415,005 and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

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Customer No.: 42717

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor Name: Alex Hsu

Residence Address: 3F, No. 42, Yuanhou Street  
Hsinchu City 300, Taiwan, R.O.C.

Dated: 2009/03/19

Alex Hsu  
Inventor Signature

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Inventor Name: Shih-Chi Fu

Residence Address: 4F, No. 41, Lane 87, Fuyang Street, Sinyi District  
Taipei City 110, Taiwan, R.O.C.

Dated: 2009/03/19

Shih-Chi Fu  
Inventor Signature

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Inventor Name: Feng-Jia Shiu

Residence Address: No. 3, Alley 22, Lane 289, Syuefu E. Road  
Jhudong Township, Hsinchu County 310, Taiwan, R.O.C.

Dated: 2009/03/19

Feng-Jia Shiu  
Inventor Signature

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Inventor Name: Chia-Shiung Tsai

Residence Address: No. 5, 50 Alley, 62 Lane, Gua-Tsuey Road East District  
Hsin-Chu, Taiwan, R.O.C.

Dated: 2009/03/19

Chia Shiung Tsai  
Inventor Signature